

MA760

Silicon epitaxial planer type (cathode common)

For switching power supply

■ Features

- Forward current (average) $I_{F(AV)}$: 5A type
- Repetitive peak reverse voltage V_{RRM} : 90V type
- Sealed in TO-220F full-pack package, with high reliability
- Cathode common dual type

■ Absolute Maximum Ratings ($T_a = 25^\circ\text{C}$)

Parameter	Symbol	Rating	Unit
Repetitive peak reverse voltage	V_{RRM}	90	V
Average forward current	$I_{F(AV)}$	5	A
Non-repetitive peak forward surge current	I_{FSM}^*	80	A
Junction temperature	T_j	- 40 to +125	$^\circ\text{C}$
Storage temperature	T_{stg}	- 40 to +125	$^\circ\text{C}$

* Sine half wave : 10ms/cycle

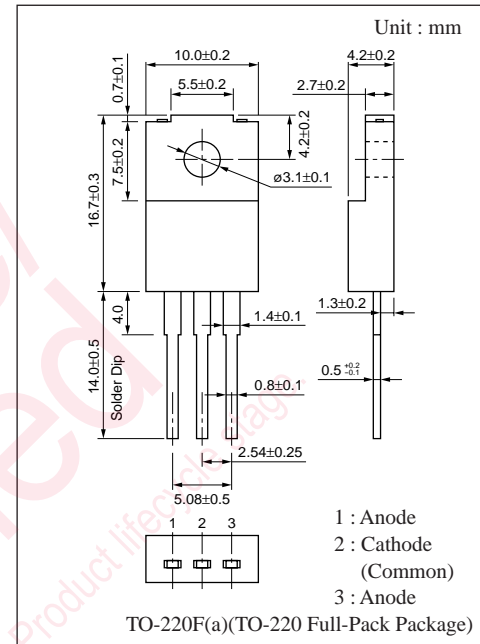
■ Electrical Characteristics ($T_a = 25^\circ\text{C}$)

Parameter	Symbol	Condition	min	typ	max	Unit
Reverse current (DC)	I_R	$V_R = 90\text{V}$			1	mA
Forward voltage (DC)	V_F	$I_F = 2.5\text{A}$			0.85	V
Thermal resistance	$R_{th(j-c)}$	Flat direct current between junction and case			3	$^\circ\text{C/W}$

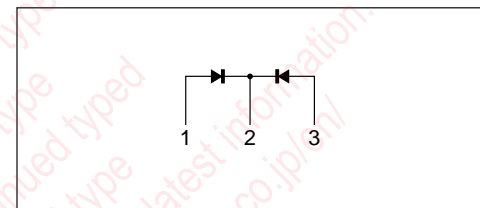
❖ Rated input/output frequency : 200MHz

■ Marking

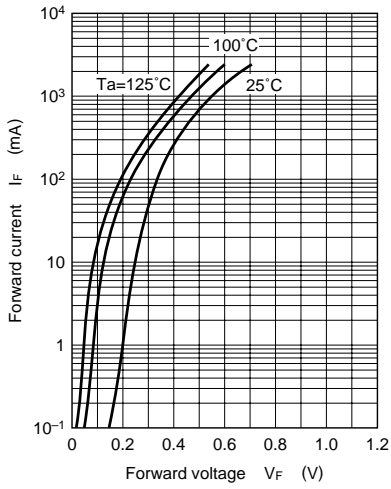
Part Number	MA760
Symbol	MA760



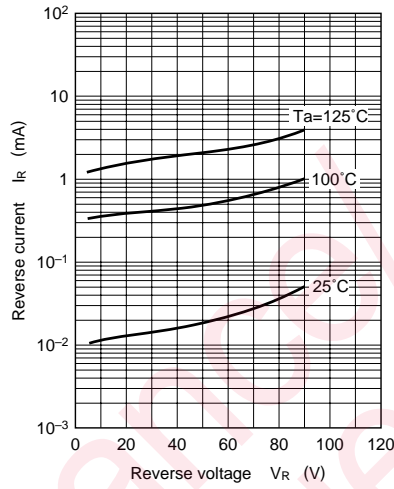
■ Internal Connection



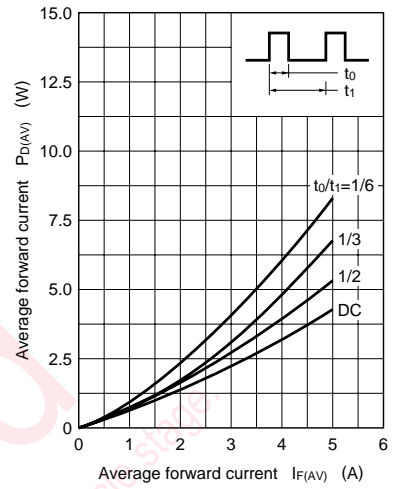
$I_F - V_F$



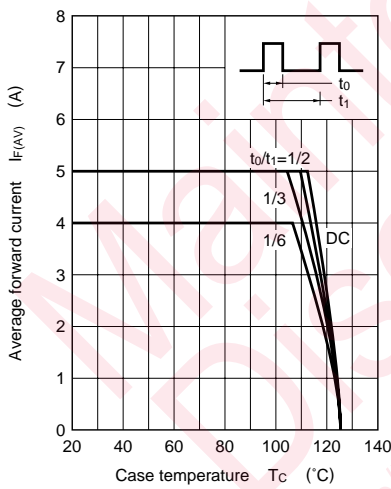
$I_R - V_R$



$P_{D(AV)} - I_{F(AV)}$



$I_{F(AV)} - T_C$



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